**Product data sheet** 

# 1. General description

Standard reverse recovery power diode in a TO247-2L package.

### 2. Features and benefits

- Low forward voltage drop
- Low leakage current
- High voltage capability
- · High inrush current capability

# 3. Applications

- · Input rectifier
- Bypass diode

### 4. Quick reference data

### Table 1. Quick reference data

| Symbol             | Parameter                           | Conditions  |      | Val | ues  |      | Unit |
|--------------------|-------------------------------------|---|------|-----|------|------|------|
| Absolute           | maximum rating                      |   |      |     |      |      |      |
| $V_{RRM}$          | repetitive peak reverse voltage     |   |      | 16  | 000  |      | V    |
| I <sub>F(AV)</sub> | average forward current             | $\delta$ = 0.5 ; square-wave pulse; $T_{mb} \le 130$ °C; Fig. 1; Fig. 2; Fig. 3 | 60   |     |      |      | Α    |
| I <sub>FSM</sub>   | non-repetitive peak forward current | $t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;<br>Fig. 4                | 950  |     |      | Α    |      |
|                    |                                     | $t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse                          | 1045 |     |      | Α    |      |
| Symbol             | Parameter                           | Conditions  |      | Min | Тур  | Max  | Unit |
| Static ch          | aracteristics                       |   |      |     |      |      |      |
| V <sub>F</sub>     | forward voltage                     | I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>                    |      | -   | 1.07 | 1.12 | V    |
|                    |                                     | I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>                   |      | -   | 0.99 | 1.05 | V    |

# 5. Pinning information

**Table 2. Pinning information** 

| Pin | Symbol | Description                        | Simplified outline | Graphic symbol     |
|-----|--------|------------------------------------|--------------------|--------------------|
| 1   | K      | cathode                            |                    | 1/ 1/4 A           |
| 2   | А      | anode                              |                    | K — A<br>001aaa020 |
| mb  | mb     | mounting base; connected to cathod | K A TO247-2L       |                    |

# 6. Ordering information

### **Table 3. Ordering information**

| Type number | Package<br>Name | Orderable part number | Packing method | Small packing quantity | Package version | Package issue date |
|-------------|-----------------|-----------------------|----------------|------------------------|-----------------|--------------------|
| WND60P16W   | TO247-2L        | WND60P16WQ            | Tube           | 30                     | TO247L-2L (L)   | 12-Nov-2020        |
|             |                 |                       |                |                        | TO247P-2L (P)   | 31-Mar-2023        |

# 7. Marking

### Table 4. Marking codes

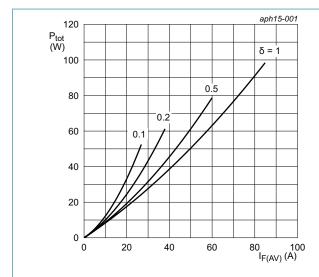
| Type number | Marking codes                |                              |  |
|-------------|------------------------------|------------------------------|--|
|             | Assembly factory: L          | Assembly factory: P          |  |
| WND60P16W   | D60P16<br>1600<br>PJLxxxx xx | D60P16<br>1600<br>PJPxxxx xx |  |

# 8. Limiting values

#### Table 5. Limiting values

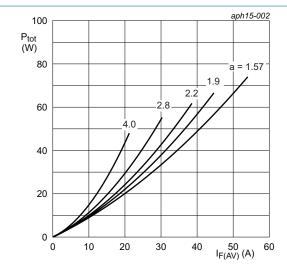
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol             | Parameter                           | Conditions  | Values     | Unit             |
|--------------------|-------------------------------------|---|------------|------------------|
| $V_{RRM}$          | repetitive peak reverse voltage     |   | 1600       | V                |
| $V_{RWM}$          | crest working reverse voltage       |   | 1600       | V                |
| $V_R$              | reverse voltage                     | DC  | 1600       | V                |
| I <sub>F(AV)</sub> | average forward current             | $\delta$ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 130 °C;<br>Fig. 1; Fig. 2; Fig. 3 | 60         | Α                |
| I <sub>FSM</sub>   | non-repetitive peak forward current | $t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;<br>Fig. 4                        | 950        | Α                |
|                    |                                     | $t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse                                  | 1045       | А                |
| l <sup>2</sup> t   | I <sup>2</sup> t for fusing         | SIN; t <sub>p</sub> = 10 ms   | 4513       | A <sup>2</sup> s |
| T <sub>stg</sub>   | storage temperature                 |   | -55 to 150 | °C               |
| T <sub>j</sub>     | junction temperature                |   | 150        | °C               |



$$\begin{split} I_{F(AV)} &= I_{F(RMS)} \times \sqrt{\delta} \\ V_o &= 0.792 \text{ V; } R_s = 0.0043 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor =  $I_{F(RMS)}/I_{F(AV)}$  $V_o$  = 0.792 V;  $R_s$  = 0.0043  $\Omega$ 

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

**WeEn Semiconductors** 

Standard power diode

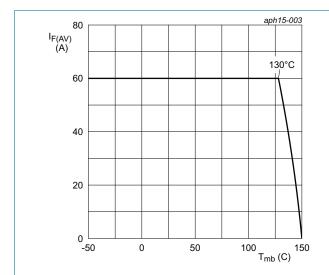


Fig. 3. Forward current as a function of mounting base temperature; maximum values

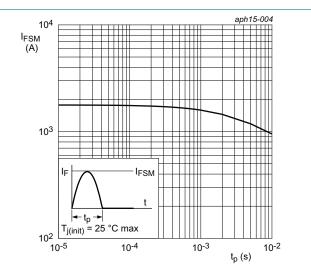


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

| Symbol                | Parameter  | Conditions  | Min | Тур | Max  | Unit |
|-----------------------|--|-------------|-----|-----|------|------|
| $R_{\text{th(j-mb)}}$ | thermal resistance<br>from junction to<br>mounting base    | Fig. 5      | -   | -   | 0.25 | K/W  |
| $R_{\text{th(j-a)}}$  | thermal resistance<br>from junction to<br>ambient free air | in free air | -   | 40  | -    | K/W  |

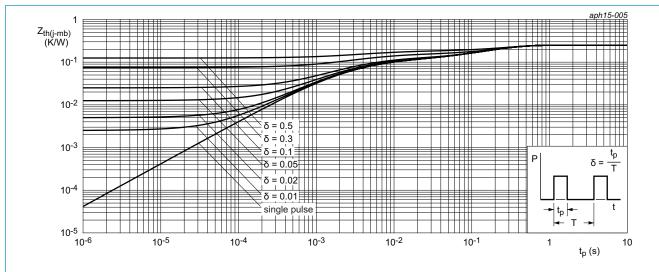
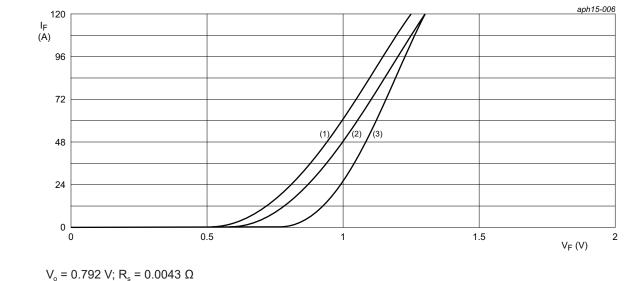


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

### **Table 7. Characteristics**

| Symbol         | Parameter       | Conditions  | Min | Тур  | Max  | Unit |
|----------------|-----------------|---|-----|------|------|------|
| Static cha     | racteristics    |   |     |      |      |      |
| $V_{F}$        | forward current | I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>  | -   | 1.07 | 1.12 | V    |
|                |                 | I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u> | -   | 0.99 | 1.05 | V    |
| I <sub>R</sub> | reverse current | V <sub>R</sub> = 1600 V; T <sub>j</sub> = 25 °C               | -   | -    | 50   | μΑ   |
|                |                 | V <sub>R</sub> = 1600 V; T <sub>j</sub> = 150 °C              | -   | -    | 1.5  | mA   |



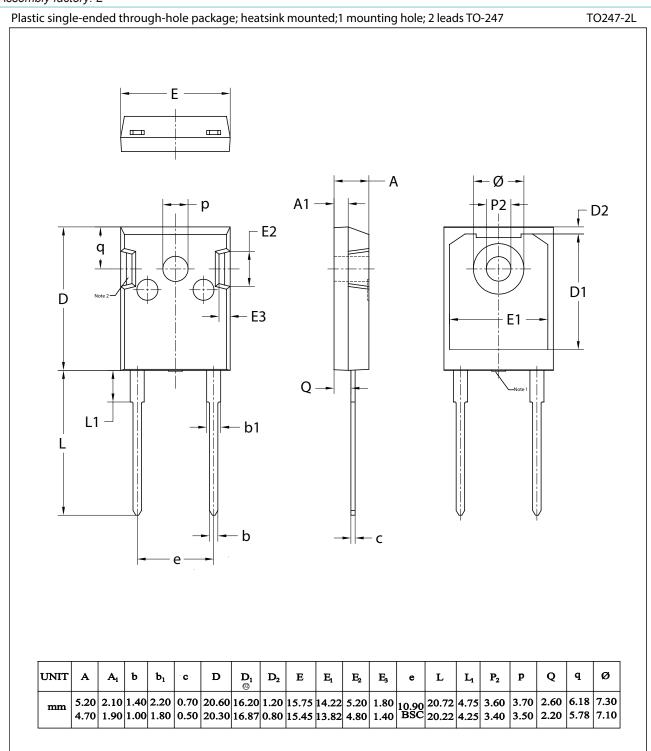
(1)  $T_j = 150$  °C; typical values (2)  $T_j = 150$  °C; maximum values

(3)  $T_i = 25$  °C; maximum values

Fig. 6. Forward current as a function of forward voltage

# 11. Package outline

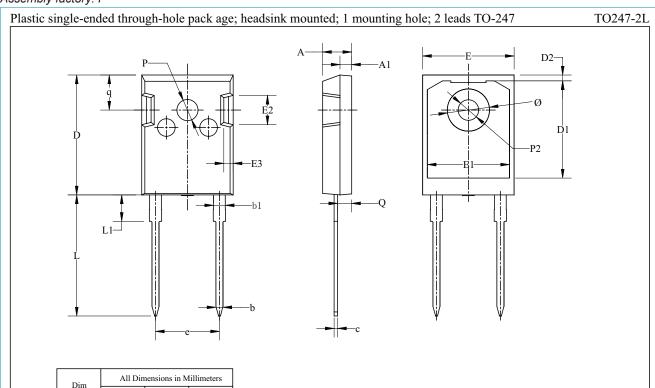
Assembly factory: L



### Note:

- 1. Mold resin protrusion max 0.127mm.
- 2. Metal exposed with Sn plating.

### Assembly factory: P



| Dim   | All Din | nensions in M | Iillimeters |
|-------|---------|---------------|-------------|
| Dilli | Min     | Тур           | Max         |
| A     | 4.70    | 4.95          | 5.20        |
| A1    | 1.90    | 2.00          | 2.10        |
| b     | 1.00    | 1.20          | 1.40        |
| b1    | 1.80    | 2.00          | 2.20        |
| с     | 0.50    | 0.60          | 0.70        |
| D     | 20.30   | 20.45         | 20.60       |
| D1    | 16.20   | 16.58         | 16.87       |
| D2    | 0.80    | 1.00          | 1.20        |
| Е     | 15.45   | 15.60         | 15.75       |
| E1    | 13.82   | 14.02         | 14.22       |
| E2    | 4.80    | 5.00          | 5.20        |
| E3    | 1.40    | 1.60          | 1.80        |
| e     |         | 10.90 BSC     |             |
| L     | 20.40   | 20.65         | 20.90       |
| L1    | 4.25    | 4.50          | 4.75        |
| P2    | 3.40    | 3.50          | 3.60        |
| P     | 3.50    | 3.60          | 3.70        |
| Q     | 2.20    | 2.40          | 2.60        |
| q     | 5.78    | 5.98          | 6.18        |
| Ø     | 7.10    | 7.19          | 7.30        |

### 12. Legal information

#### Data sheet status

| Document status [1][2]               | Product status [3] | Definition  |
|--------------------------------------|--------------------|---|
| Objective<br>[short] data<br>sheet   | Development        | This document contains data from the objective specification for product development. |
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